

AMENDMENTS TO THE CLAIMS:

Please replace all prior listings of claims with that which appears below, in which the claims have been amended to read as follows:

1. (Currently Amended) Soldering material comprising an alloy ~~that in addition to~~ consisting essentially of Sn (tin) ~~as the major constituent, comprises~~ 10 wt.% or less Ag (silver), 10 wt.% or less Bi (bismuth), 10 wt.% or less Sb (antimony), and 3 wt.% or less Cu (copper), ~~wherein the alloy further comprises~~ and 1.0 wt.% or less Ni (nickel).

2. (Currently Amended) Soldering material comprising a plurality of soldering components ~~with such~~ and solder alloy compositions ~~and contents in the soldering material that on~~ whereupon fusing the soldering components an alloy is formed that, in addition to Sn (tin) ~~as the major constituent,~~ comprises 10 wt.% or less Ag (silver), 10 wt.% or less Bi (bismuth), 10 wt.% or less Sb (antimony), and 3 wt.% or less Cu (copper), ~~wherein at least one of the soldering components further comprises Ni (nickel) in such an amount that the alloy comprises~~ and 1.0 wt.% or less Ni.

3. (Previously Presented) Soldering material according to Claim 1 wherein the alloy comprises 2 to 5 wt.% Ag, 1 to 3 wt.% Bi, 1 to 3 wt.% Sb, 0.5 to 1.5 wt.% Cu and 0.05 to 0.3 wt.% Ni.

4. (Currently Amended) Soldering material according to Claim 2 ~~wherein~~ further comprising a soldering component M1 and a ~~further~~ soldering component M2 ~~are provided in which~~ wherein the soldering component M1, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 3 to 12 wt.% Bi, 0.5 to 1.5 wt.% Cu and 0.1 to 0.3 wt.% Ni and the ~~further~~ soldering component M2, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 0.5 to 1.5 wt.% Cu, 1 to 5 wt.% Sb and 1.0 wt.% Ni.

5. (Currently Amended) Soldering material according to Claim 2 ~~wherein~~ further comprising a soldering component M1 and a ~~further~~ soldering component M2 ~~are provided in which~~ wherein the soldering component M1, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 3 to 6 wt.% Bi, 1 to 3 wt.% Sb and 0.5 to 1.5 wt.% Cu and the ~~further~~ soldering component M2, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 0.5 to 1.5 wt.% Cu and 1.0 wt.% Ni.

6. (Currently Amended) Soldering material according to Claim 4 wherein the soldering component M1 and the ~~further~~ soldering component M2 are combined in the ratio $M1:M2 = 1:1.5$ to 9, based on the weight of M1 and M2.

7. (Currently Amended) Soldering material according to Claim 1 wherein in the alloy there exists a ratio Sb:Bi of 1:1.5 to 3, ~~particularly a ratio of 1:2,~~ based on the weight of Sb and Bi.

8. (Original) Soldering material according to Claim 7 wherein the alloy exhibits a Ni-content of 0.05 to 0.2 wt.%.

9. (Currently Amended) Soldering material according to Claim 1 wherein the alloy composition is $\text{SnAg}3.3\text{-}4.7\text{Cu}0.3\text{-}1.7\text{Bi}2\text{Sb}1\text{Ni}0.2$.

10. (Currently Amended) Soldering material according to Claim 2 wherein a soldering component M1 with the alloy ~~composition~~ $\text{SnAg}3.8\text{Cu}0.7\text{Bi}10\text{Ni}0.15$ and a further soldering component M2 with the alloy ~~composition~~ $\text{SnAg}3.8\text{Cu}0.7\text{Sb}2.0\text{Ni}0.15$ are provided.

11. (Original) Soldering material according to Claim 10 wherein the contents of the soldering component M1 and the further soldering component M2 in the soldering material form the ratio $M1:M2 = 30 \text{ wt.}\% : 70 \text{ wt.}\%$.

12. (Previously Presented) Soldering material according to Claim 2 wherein the alloy comprises 2 to 5 wt.% Ag, 1 to 3 wt.% Bi, 1 to 3 wt.% Sb, 0.5 to 1.5 wt.% Cu and 0.05 to 0.3 wt.% Ni.

13. (Previously Presented) Soldering material according to Claim 5 wherein the soldering component M1 and the further soldering component M2 are combined in the ratio $M1:M2 = 1:1.5$ to 9, based on the weight of M1 and M2.

14. (Currently Amended) Soldering material according to Claim 2 wherein in the alloy there exists a ratio Sb:Bi of 1:1.5 to 3, ~~particularly a ratio of 1:2,~~ based on the weight of Sb and Bi.

15. (Currently Amended) Soldering material according to Claim 3 wherein in the alloy there exists a ratio Sb:Bi of 1:1.5 to 3, ~~particularly a ratio of 1:2,~~ based on the weight of Sb and Bi.

16. (Currently Amended) Soldering material according to Claim 4 wherein in the alloy there exists a ratio Sb:Bi of 1:1.5 to 3, ~~particularly a ratio of 1:2,~~ based on the weight of Sb and Bi.

17. (Currently Amended) Soldering material according to Claim 5 wherein in the alloy there exists a ratio Sb:Bi of 1:1.5 to 3, ~~particularly a ratio of 1:2,~~ based on the weight of Sb and Bi.

18. (Currently Amended) Soldering material according to Claim 6 wherein in the alloy there exists a ratio Sb:Bi of 1:1.5 to 3, ~~particularly a ratio of 1:2,~~ based on the weight of Sb and Bi.